

L Number	Hits	Search Text	DB	Time stamp
1	448237	through adj hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:43
2	1677983	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:41
3	26879	(through adj hole) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:42
4	64608	anodi\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:42
5	626	((through adj hole) with substrate) and anodi\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:42
6	448237	through adj1 hole	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:43
7	626	((through adj1 hole) with substrate) and anodi\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:44
8	0	((((through adj1 hole) with substrate) and anodi\$8) not ((through adj hole) with substrate) and anodi\$8)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:44
9	79	((((through adj1 hole) with substrate) and anodi\$8) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:45
-	5063	((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:16
-	52	((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 01:52
-	24	((((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) and ((rear or back) same surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:19

-	22	((((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) and ((rear or back) same surface same (wafer or substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:54
-	2	((((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) and ((rear or back) same surface)) not (((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) and ((rear or back) same surface same (wafer or substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:26
-	28	((((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) not (((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) and ((rear or back) same surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:34
-	6075	((438/408) or (438/430) or (438/431) or (438/432) or (438/719) or (438/735) or (438/738) or (438/750) or (438/751) or (438/753) or (438/756) or (438/762) or (438/769) or (438/770) or (438/771) or (438/772) or (438/773) or (438/774) or (438/787) or (438/788) or (438/928) or (438/959) or (438/977)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:37
-	128	((438/408) or (438/430) or (438/431) or (438/432) or (438/719) or (438/735) or (438/738) or (438/750) or (438/751) or (438/753) or (438/756) or (438/762) or (438/769) or (438/770) or (438/771) or (438/772) or (438/773) or (438/774) or (438/787) or (438/788) or (438/928) or (438/959) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:37
-	106	((438/408) or (438/430) or (438/431) or (438/432) or (438/719) or (438/735) or (438/738) or (438/750) or (438/751) or (438/753) or (438/756) or (438/762) or (438/769) or (438/770) or (438/771) or (438/772) or (438/773) or (438/774) or (438/787) or (438/788) or (438/928) or (438/959) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide)) not (((438/466) or (438/469) or (438/599) or (438/620) or (438/631) or (438/633) or (438/666) or (438/667) or (438/690) or (438/691) or (438/692) or (438/693) or (438/928) or (438/977)).CCLS.) and ((anodic or anodiz\$5) same oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:53

-	1523	438/\$.ccls. and ((anodic or anodiz\$5) same oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:54
-	894	(438/\$.ccls. and ((anodic or anodiz\$5) same oxide)) and ((anodic or anodiz\$5) same oxide same (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:56
-	566	((438/\$.ccls. and ((anodic or anodiz\$5) same oxide)) and ((anodic or anodiz\$5) same oxide same (wafer or substrate))) and (hole or via or (contact adj hole) or (through adj hole))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:57
-	498	((438/\$.ccls. and ((anodic or anodiz\$5) same oxide)) and ((anodic or anodiz\$5) same oxide same (wafer or substrate))) and ((substrate or wafer) same (hole or via or (contact adj hole) or (through adj hole) or opening))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:58
-	457	((438/\$.ccls. and ((anodic or anodiz\$5) same oxide)) and ((anodic or anodiz\$5) same oxide same (wafer or substrate))) and ((substrate or wafer) same (hole or via or (contact adj hole) or (through adj hole) or opening))) and (electrode or plug or conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 00:58
-	196	((438/\$.ccls. and ((anodic or anodiz\$5) same oxide)) and ((anodic or anodiz\$5) same oxide same (wafer or substrate))) and ((substrate or wafer) same (hole or via or (contact adj hole) or (through adj hole) or opening))) and ((expos\$3 or protrud\$3) same (electrode or plug or conduct\$3) same (substrate or wafer))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 01:47
-	115	(NEMOTO same YOSHIHIKO) OR (HOSHINO same MASATAKA) OR (YONEMURA same HITOSHI)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 01:52
-	0	((NEMOTO same YOSHIHIKO) OR (HOSHINO same MASATAKA) OR (YONEMURA same HITOSHI)) and ((anodic or anodiz\$5) same oxide)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 01:52
-	1	((NEMOTO same YOSHIHIKO) OR (HOSHINO same MASATAKA) OR (YONEMURA same HITOSHI)) and (anodic or anodiz\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/03 19:41